

XP-002241964

AN - 2001-532489 [59]

AP - JP19990351786 19991210

CPY - YAWA

DC - L02 L03 P61

FS - CPI;GMPI

IC - B24B37/00 ; B24B53/12 ; B24D3/00 ; B24D3/06

MC - L02-F L04-C26

PA - (YAWA) NIPPON STEEL CORP

PN - JP2001162540 A 20010619 DW200159 B24D3/00 004pp

PR - JP19990351786 19991210

XA - C2001-158839

XIC - B24B-037/00 ; B24B-053/12 ; B24D-003/00 ; B24D-003/06

XP - N2001-395534

AB - JP2001162540 NOVELTY - A dresser of abrasive cloth contains a mono-layer of brazing diamond grinding particles with joining alloy, formed on a support member. The joining alloy contains more than 20 mass% of element(s) chosen from titanium, zirconium, chromium, tantalum or niobium.

- USE - For semiconductor substrates.

- ADVANTAGE - The dresser has improved life span, and effectively and inexpensively removes clogging of abrasive cloth in Chemical Mechanical Planarization of semiconductor wafer. Frequent exchange of dresser is prevented.

- (Dwg.0/0)

IW - DRESS ABRASION CLOTH SEMICONDUCTOR SUBSTRATE MONO LAYER BRAZE DIAMOND GRIND PARTICLE JOIN ALLOY COMPRISE TITANIUM ZIRCONIUM CHROMIUM TANTALUM NIOBIUM FORMING SUPPORT MEMBER

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NC - 001

OPD - 1999-12-10

ORD - 2001-06-19

PAW - (YAWA) NIPPON STEEL CORP

TI - Dresser of abrasive cloth for semiconductor substrates, has mono-layer of brazing diamond grinding particles with joining alloy comprising titanium, zirconium, chromium, tantalum or niobium, formed on support member